

Chitosan–Silica Composite Aerogel for the Adsorption of Cupric Ions

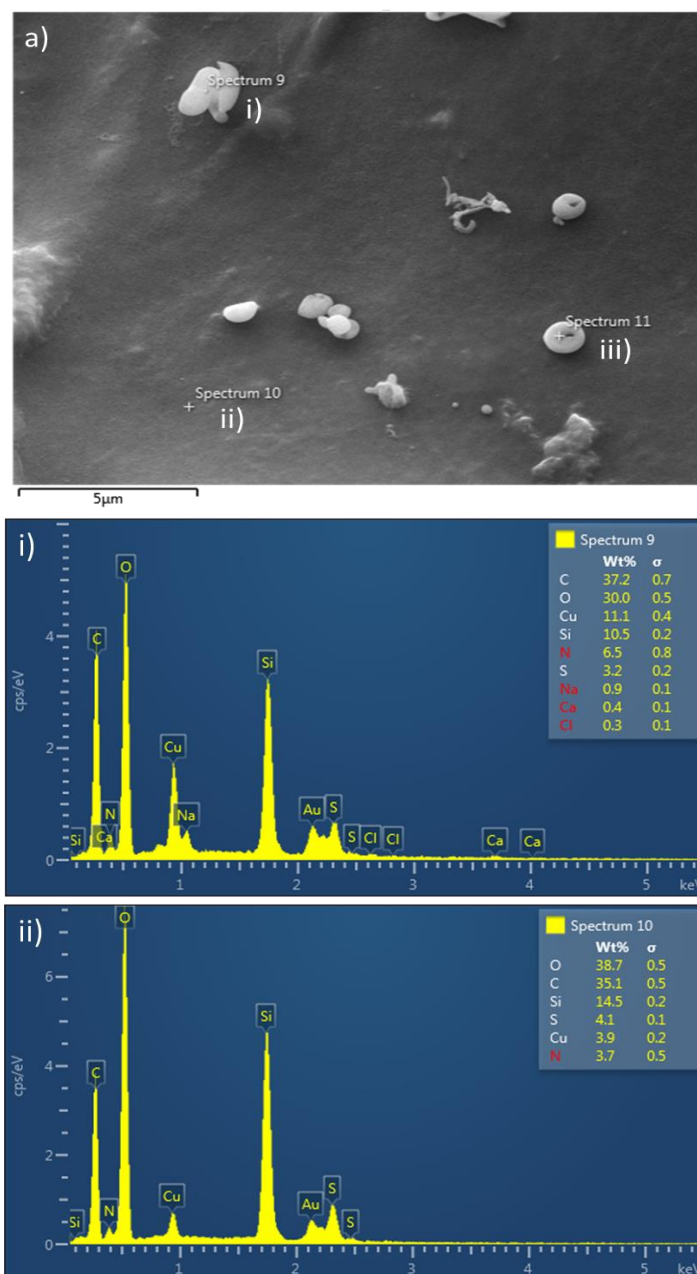
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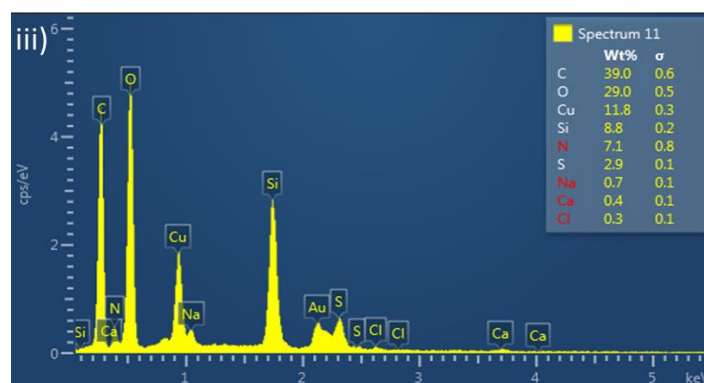


Figure S1. SEM image (a) of the copper-loaded chitosan-silica aerogel with three regions highlighted (i, ii) and iii); EDX spectrum of each region (i, ii) and iii)), showing the main components of the aerogel after Cu(II) adsorption.

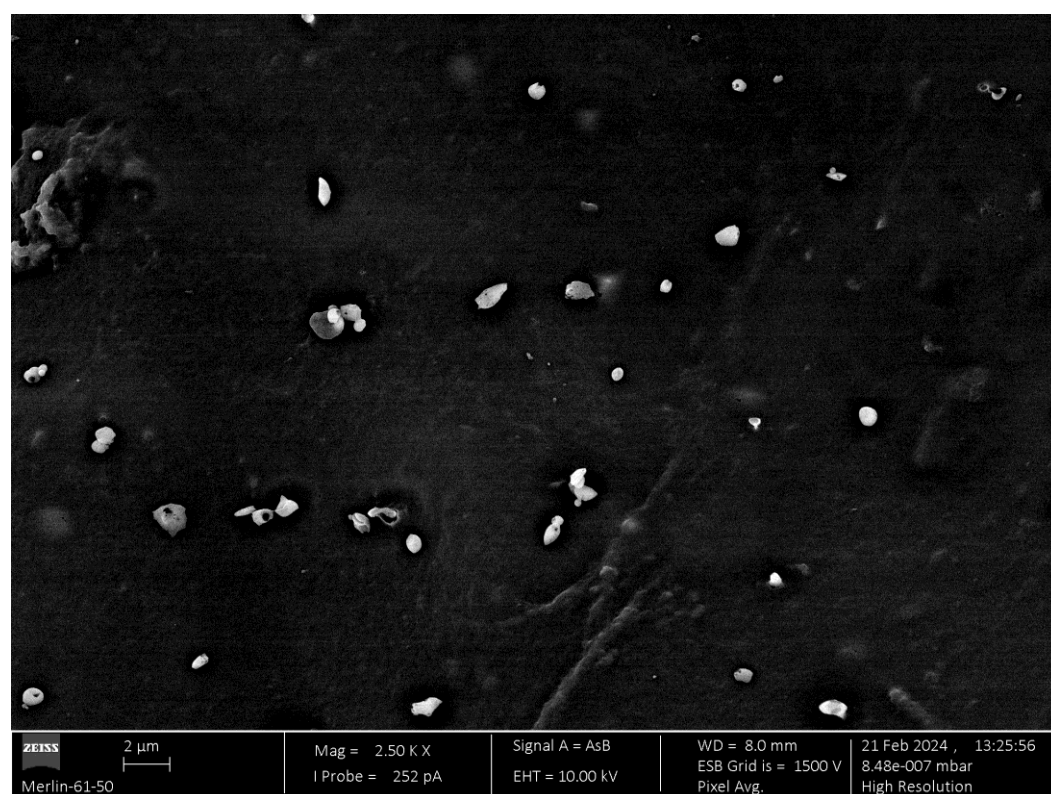


Figure S2. Microstructure of the copper-loaded chitosan-silica aerogel at 2.50k \times obtained by backscattered electron SEM imaging.

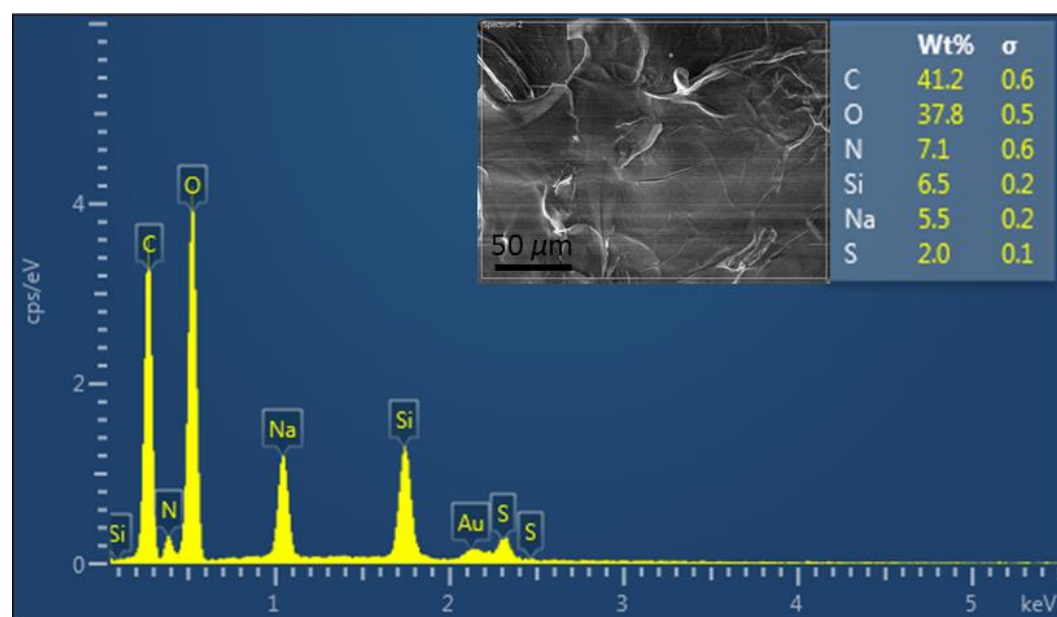


Figure S3. EDX spectrum of the neat chitosan-silica aerogel.